

19th FRUCT Conference



# Methods for TSVs placement in 3D Network-on-chip

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## Outline

- 1. Introduction
- 2. Problems of 3D NoC design
- 3. Placement TSV nodes on the dies with
  - the **<u>same</u>** topologies
- Placement TSV nodes on the dies with the <u>different</u> topologies



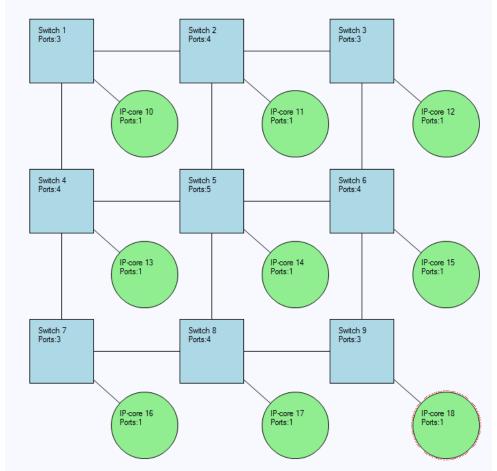
#### Introduction

## Network-on-Chip

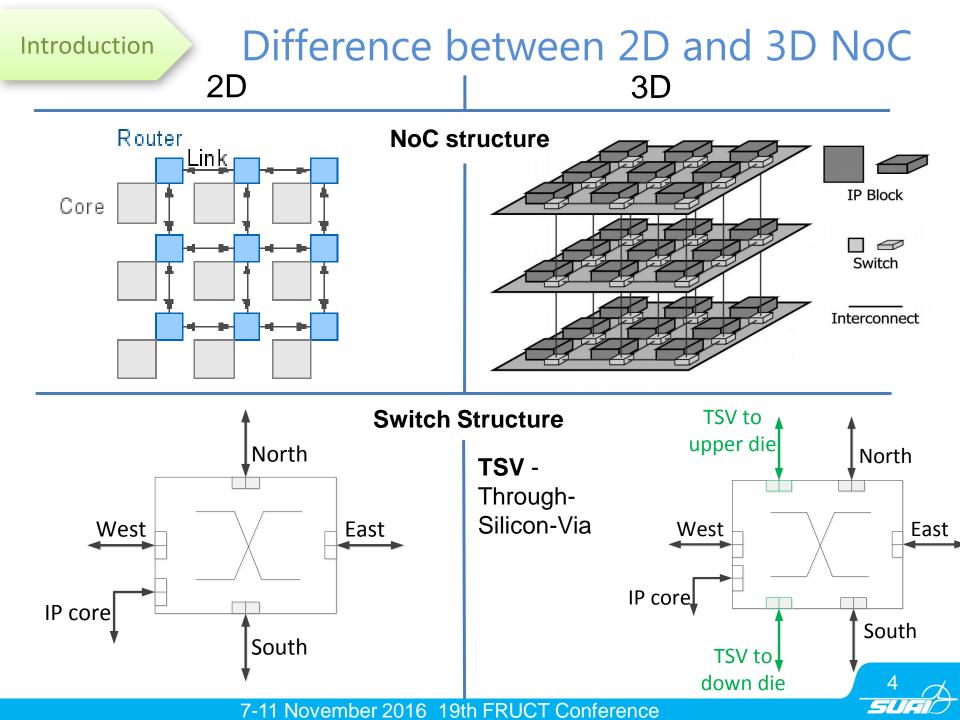
Network-on-Chip (NoC) – a communication subsystem between intellectual property (IP) cores in the System-on-Chip (SoC)

NoC includes:

- Terminal nodes (IP cores)
- Switch nodes
- Interconnect







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the same topologies

Placement TSV nodes on the dies with the <u>different</u> topologies





## Problems of 3D NoC design

Modern 3D NoC development is complex task

Developer has to solve different problems:

- IP blocks placement on the die
- Energy consumption limitation
- System performance improvement
- Organization of vertical links between dies in the 3D stack (TSV placement)



Design problems

## TSV placement problems



Design problems

## TSV placement problems

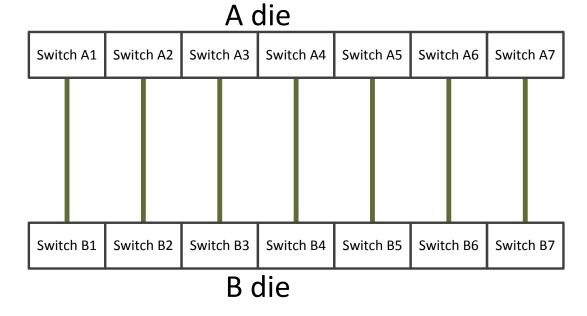
TSVs heat dissipation



TSVs heat dissipation

Design

problems





A die

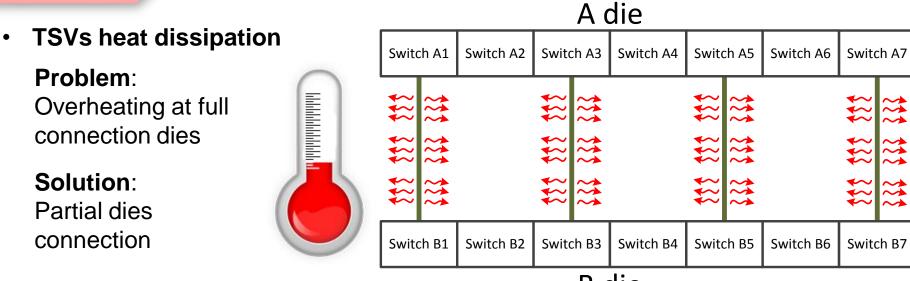
<ul> <li>TSVs heat dissipation</li> </ul>	Switch A1	Switch A2
Problem: Overheating at full connection dies		

Design

problems

	Swite	ch A1	A1 Switch A2		Switch A2 Switch A3		ch A3	Swite	ch A4	Switch A5		Switch A6		Switch A7	
	\$ <b>* * * * * * *</b>	2 2 2 2 2 2 2 2 2	\$ \$\$\$ \$\$\$	111 111 1	\$ \$\$\$ \$\$\$	2 2 2 2 2 2 2 2 2	\$ \$\$\$ \$\$\$	111 111 1	\$ \$\$\$ \$\$\$	2 2 2 2 2 2 2 2 2	\$ \$ \$ \$ \$ \$ \$	111 111 1	\$ \$\$\$ \$\$\$	111 111 1	
	*~	~	*~	~	**	~	*~	~	*~	~	**	~	*~	~	
/	Swite	ch B1	Swite	ch B2	Swite	ch B3	Swite	ch B4	Swite	ch B5	Swite	ch B6	Swite	ch B7	
,						Вс	die								



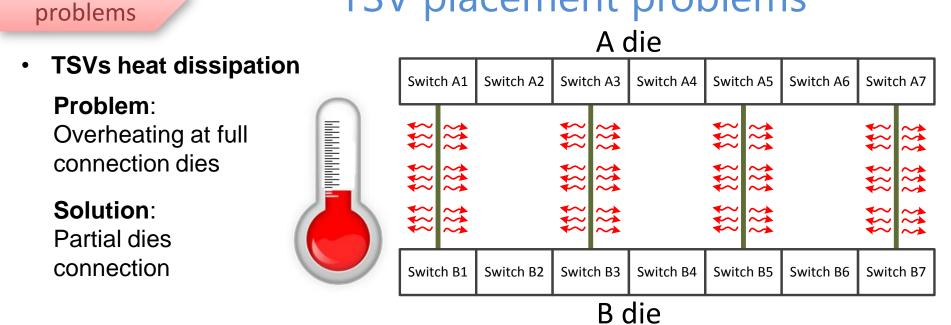


Design

problems

B die

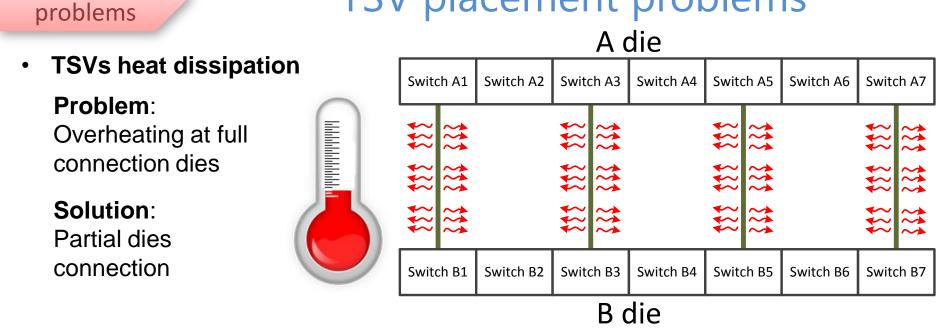




Bottleneck in data transfer from die to die

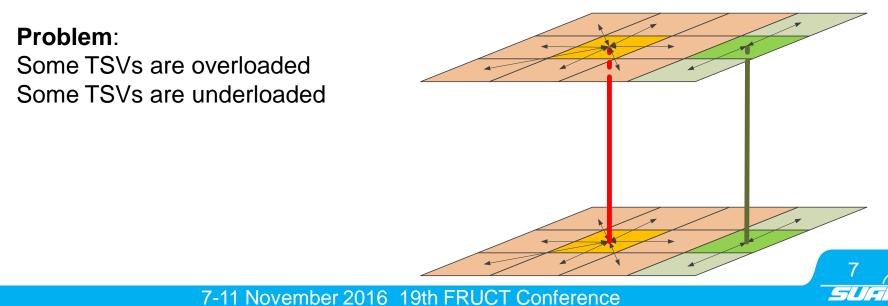
Design

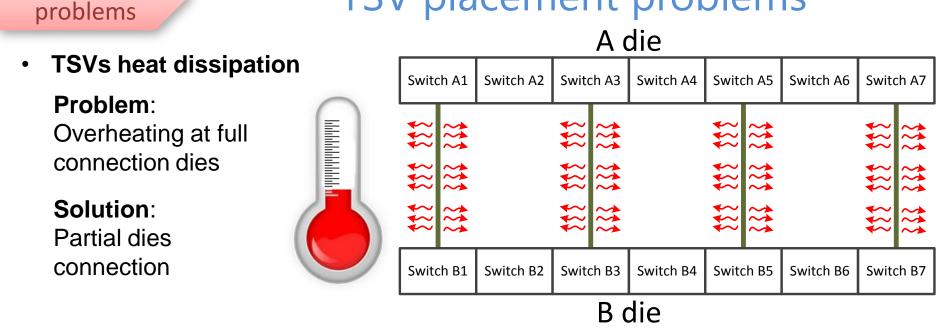




• Bottleneck in data transfer from die to die

Design





• Bottleneck in data transfer from die to die

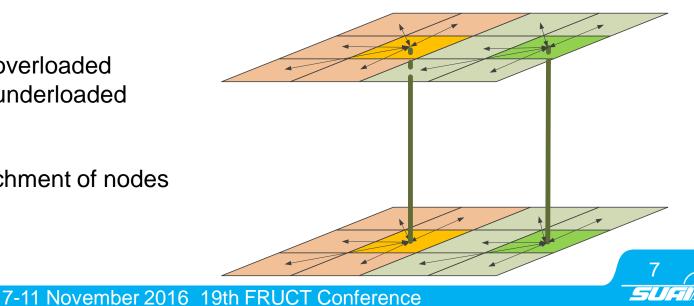
#### Problem:

Design

Some TSVs are overloaded Some TSVs are underloaded

#### Solution:

The uniform attachment of nodes to each TSV



# P – median problem in 3D NoC design

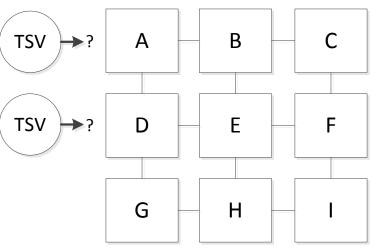
- The problem of placement specific nodes (P nodes), such that for each pair of nodes the Chebyshev distance is not less than H and the number of attached nodes should be near equal among regions
- **Chebyshev distance** (H) is the maximal absolute componentwise difference

 $\mathsf{H}(\vec{x}, \vec{y}) = \max_{1 \le i \le n} |x_i - y_i|$ 

Design

problems

• Necessary condition:  $V = V_P \cup V_{Att}$ , where  $V_P$  - set of medians,  $V_{Att}$  - set of attached nodes, V - set of all nodes in the graph





# P – median problem in 3D NoC design

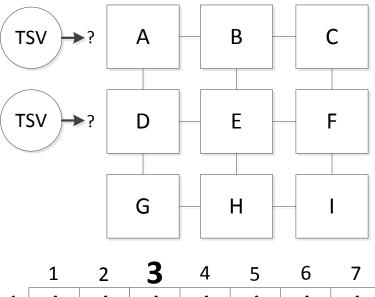
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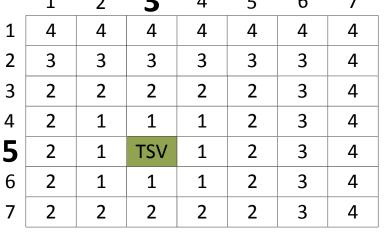
$$\mathsf{H}(\vec{x}, \vec{y}) = \max_{1 \le i \le n} |x_i - y_i|$$

Design

problems

• Necessary condition:  $V = V_P \cup V_{Att}$ , where  $V_P$  - set of medians,  $V_{Att}$  - set of attached nodes, V - set of all nodes in the graph







# P – median problem in 3D NoC design

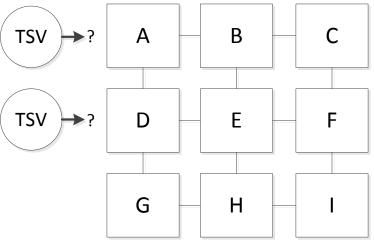
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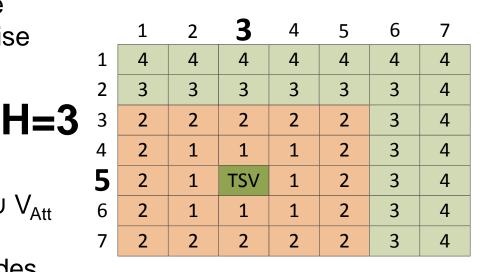
$$\mathsf{H}(\vec{x}, \vec{y}) = \max_{1 \le i \le n} |x_i - y_i|$$

Design

problems

- $\max_{1 \le i \le n} |x_i y_i|$
- Necessary condition: V = V<sub>P</sub> ∪ V<sub>Att</sub>, where V<sub>P</sub> set of medians, V<sub>Att</sub> set of attached nodes, V set of all nodes in the graph







## Outline

- 1. Introduction
- 2. Problems of 3D NoC design
- 3. Placement TSV nodes on the dies with the **same** topologies
- Placement TSV nodes on the dies with the <u>different</u> topologies



#### Same topologies Placement TSV nodes on the dies with the <u>same</u> topologies

**Problem**: Find the location of P TSVs on the die

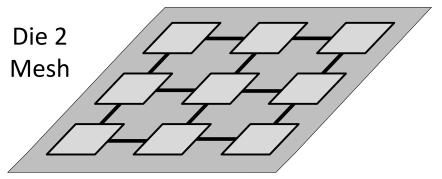
**Goal**: Connect the dies in 3D stack without overheating and to provide the maximal uniform loading of connections between the dies

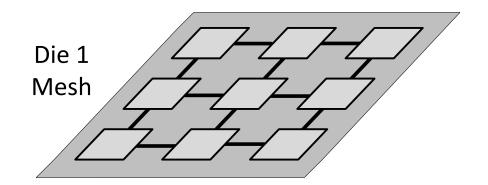
#### Input data:

- Topology
- Number of TSVs (P)
- Distance between TSVs (H)

#### Output data:

 Set of solutions with locations of P TSVs







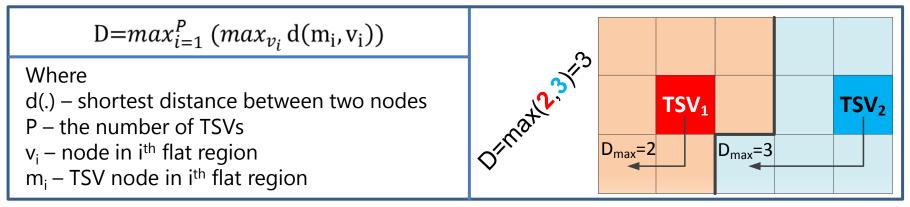
## Criteria for choosing best solution on the die

The following criteria are applied when we choose best solution on the die:

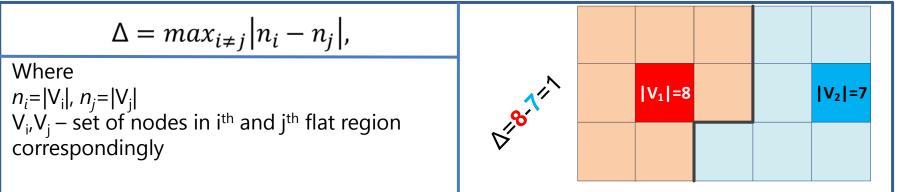
Same

topologies

• **Distance** [D, hops] – the maximal distance between TSV node and the farthest node in it's **flat** region among all TSV nodes:



 Difference of TSVs load [Δ, Number nodes] – maximal absolute difference of nodes count among all pairs of flat regions:





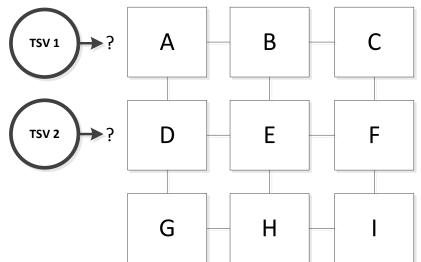
It is necessary to place two TSVs (P = 2) in a 3x3 NoC with Mesh topology, and achieve a minimal distance from the TSV node to other nodes, achieve the maximal uniform attachment of nodes.

Same

topologies

1. Building a matrix of shortest distances.

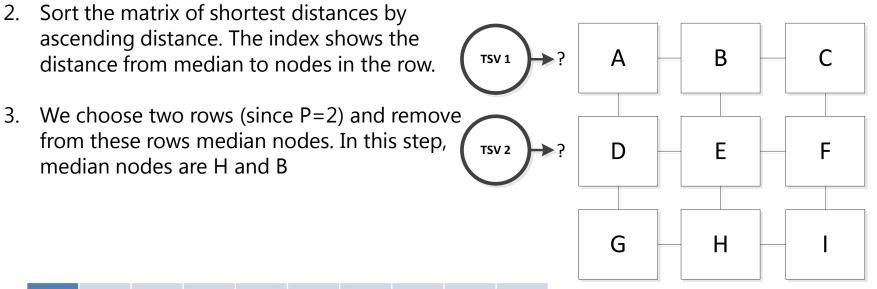
	Α	В	С	D	Ε	F	G	н	I.
Α	0	1	2	1	2	3	2	3	4
В	1	0	1	2	1	2	3	2	3
С	2	1	0	3	2	1	4	3	2
D	1	2	3	0	1	2	1	2	3
Е	2	1	2	1	0	1	2	1	2
F	3	2	1	2	1	0	3	2	1
G	2	3	4	1	2	3	0	1	2
Н	3	2	3	2	1	2	1	0	1
1	4	3	2	3	2	1	2	1	0



Input data:

- Mesh 3x3
- P=2



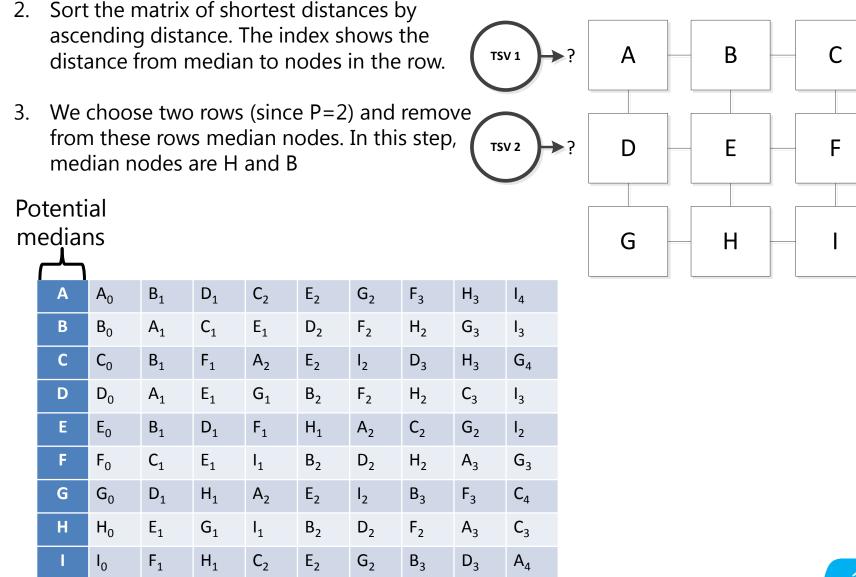


Α	A <sub>0</sub>		$D_1$		E <sub>2</sub>	G <sub>2</sub>	F <sub>3</sub>	H <sub>3</sub>	$I_4$
В	B <sub>0</sub>	$A_1$	C <sub>1</sub>	E <sub>1</sub>	D <sub>2</sub>	F <sub>2</sub>	H <sub>2</sub>	G <sub>3</sub>	I <sub>3</sub>
С	<b>C</b> <sub>0</sub>	B <sub>1</sub>	$F_1$	A <sub>2</sub>		I <sub>2</sub>	-	J	G <sub>4</sub>
D	D <sub>0</sub>	$A_1$	E <sub>1</sub>	$G_1$	B <sub>2</sub>	$F_2$	H <sub>2</sub>	C <sub>3</sub>	I <sub>3</sub>
E	E <sub>0</sub>	B <sub>1</sub>	$D_1$	F <sub>1</sub>	$H_1$	A <sub>2</sub>	_	_	I <sub>2</sub>
F	F <sub>0</sub>	C <sub>1</sub>	E <sub>1</sub>	$I_1$	B <sub>2</sub>	D <sub>2</sub>	H <sub>2</sub>	A <sub>3</sub>	G <sub>3</sub>
G	G <sub>0</sub>	$D_1$	H <sub>1</sub>	A <sub>2</sub>	E <sub>2</sub>	I <sub>2</sub>	B <sub>3</sub>	$F_3$	C <sub>4</sub>
н	H <sub>0</sub>	E <sub>1</sub>	$G_1$	$I_1$	B <sub>2</sub>	D <sub>2</sub>	F <sub>2</sub>	A <sub>3</sub>	C <sub>3</sub>
I	I <sub>0</sub>	F <sub>1</sub>	H <sub>1</sub>	C <sub>2</sub>	E <sub>2</sub>	G <sub>2</sub>	B <sub>3</sub>	D <sub>3</sub>	A <sub>4</sub>

Same

topologies

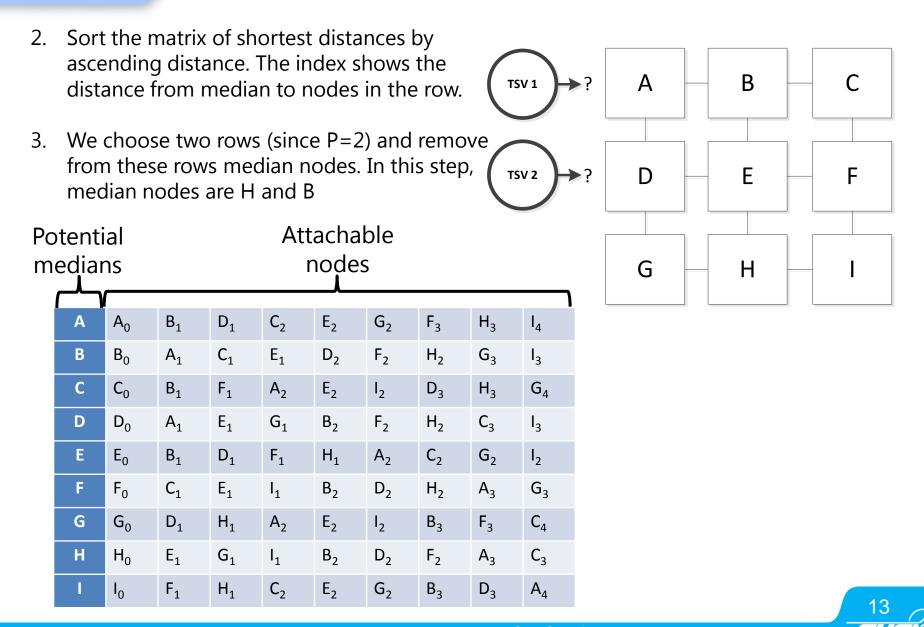




Same

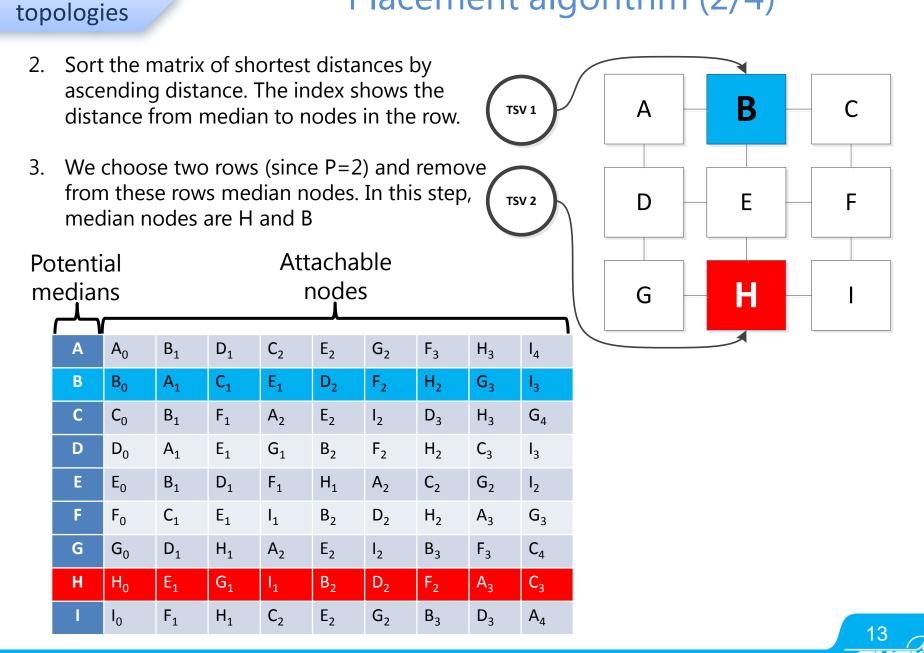
topologies



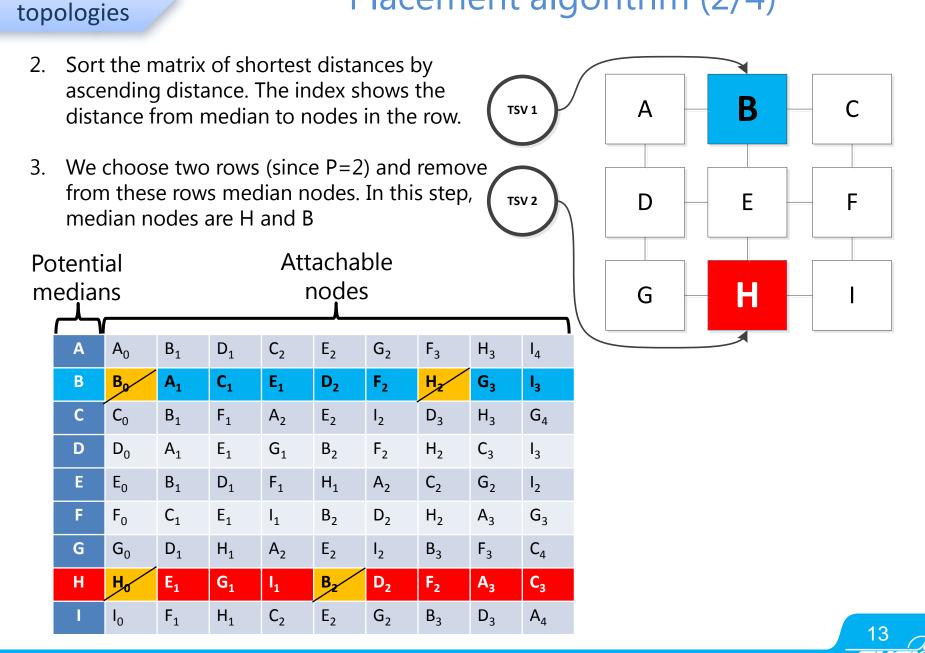


Same

topologies



Same



Same

4. We derive a new table that contains attachable nodes, medians, to which they are attached and the distance to them in ascending order.

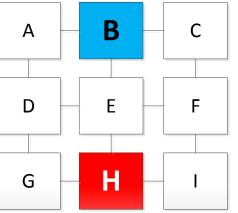
Attachable nodes	А	С	E	G	I	D	F	А	С	G	I
Medians	В	В	B,H	Н	Н	B,H	B,H	н	Н	В	В
Distance	1	1	1	1	1	2	2	3	3	3	3

Same

topologies

5. We select connection to p-median with the minimal distance for each node. From the resulting table you can uniquely identify nodes that can be attached to only one median.

Attachable nodes	А	С	E	G	I	D	F	А	С	G	I
Medians	В	В	B,H	н	н	B,H	B,H	н	н	В	В
Distance	1	1	1	1	1	2	2	3	3	3	3





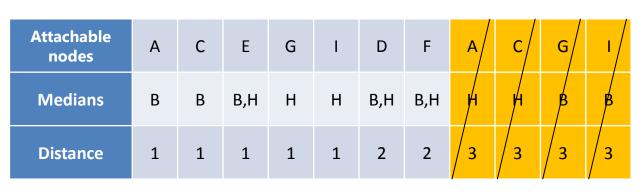
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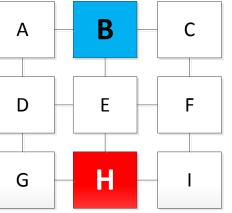
Attachable nodes	А	С	E	G	I	D	F	А	С	G	I
Medians	В	В	B,H	н	н	B,H	В,Н	н	Н	В	В
Distance	1	1	1	1	1	2	2	3	3	3	3

Same

topologies

5. We select connection to p-median with the minimal distance for each node. From the resulting table you can uniquely identify nodes that can be attached to only one median.







4. We derive a new table that contains attachable nodes, medians, to which they are attached and the distance to them in ascending order.

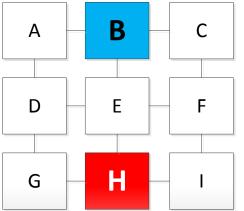
Attachable nodes	А	С	E	G	I	D	F	А	С	G	I
Medians	В	В	B,H	н	н	B,H	B,H	н	н	В	В
Distance	1	1	1	1	1	2	2	3	3	3	3

5. We select connection to p-median with the minimal distance for each node. From the resulting table you can uniquely identify nodes that can be attached to only one median.

Attachable nodes	А	С	E	G	I	D	F
Medians	В	В	В,Н	н	н	B,H	B,H
Distance	1	1	1	1	1	2	2

Same

topologies





4. We derive a new table that contains attachable nodes, medians, to which they are attached and the distance to them in ascending order.

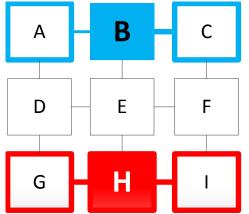
Attachable nodes	А	С	E	G	I	D	F	А	С	G	I
Medians	В	В	B,H	н	н	B,H	B,H	н	н	В	В
Distance	1	1	1	1	1	2	2	3	3	3	3

5. We select connection to p-median with the minimal distance for each node. From the resulting table you can uniquely identify nodes that can be attached to only one median.

Attachable nodes	А	С	E	G	I	D	F
Medians	В	В	B,H	н	н	B,H	B,H
Distance	1	1	1	1	1	2	2

Same

topologies





4. We derive a new table that contains attachable nodes, medians, to which they are attached and the distance to them in ascending order.

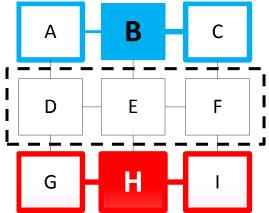
Attachable nodes	А	С	E	G	I	D	F	А	С	G	I
Medians	В	В	B,H	н	Н	B,H	B,H	н	Н	В	В
Distance	1	1	1	1	1	2	2	3	3	3	3

5. We select connection to p-median with the minimal distance for each node. From the resulting table you can uniquely identify nodes that can be attached to only one median.

Attachable nodes	E	D	F
Medians	B,H	B,H	B,H
Distance	1	2	2

Same

topologies





Α

D

B

E

6. Distribute remaining nodes on the medians with the maximal uniformly attachment

Attachable nodes	Е	D	F
Medians	B,H	B,H	B,H
Distance	1	2	2

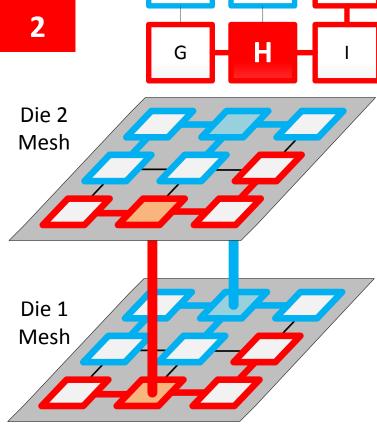
Solution checking:

- V<sub>P</sub>UV<sub>Att</sub>=V
- H=2

Same

topologies

- D=max(d(V<sub>P</sub>, V<sub>Att</sub>)) = 2 hops
- Δ=1 node





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the same topologies

 Placement TSV nodes on the dies with the <u>different</u> topologies



# Placement TSV nodes on the dies with the <u>different</u> topologies

**Problem**: Find the location of p TSVs for dies with different topologies

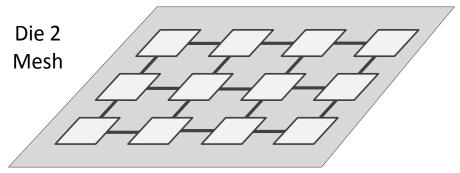
**Goal**: Connect the dies in 3D stack without overheating and to provide the maximal uniform loading of connections between the dies

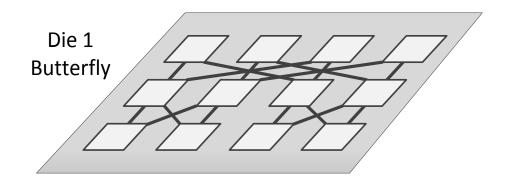
#### Input data:

- Topologies
- Number of TSVs (p)
- Distance between TSVs (H)

#### Output data:

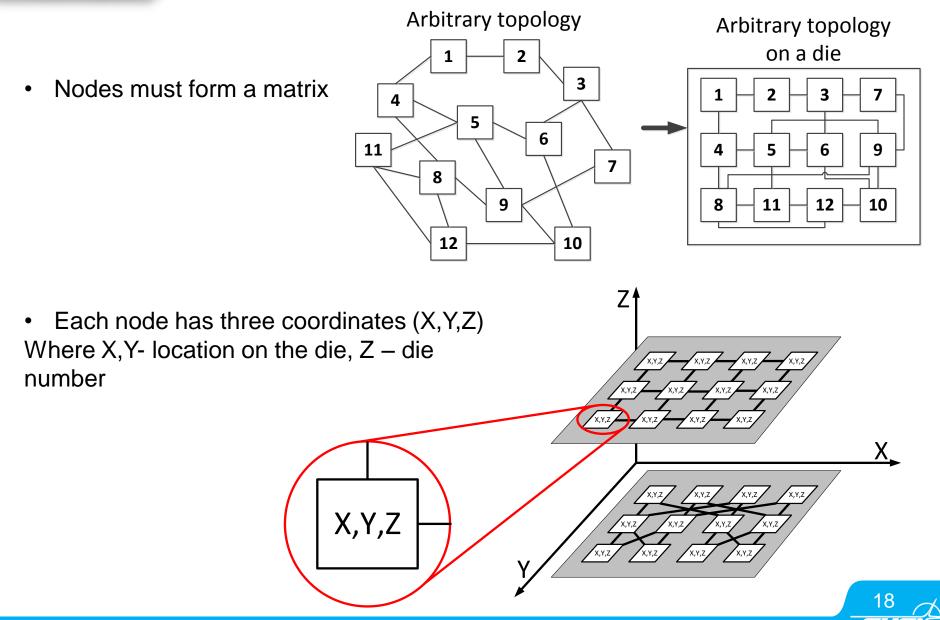
 Set of solutions with locations of p TSVs





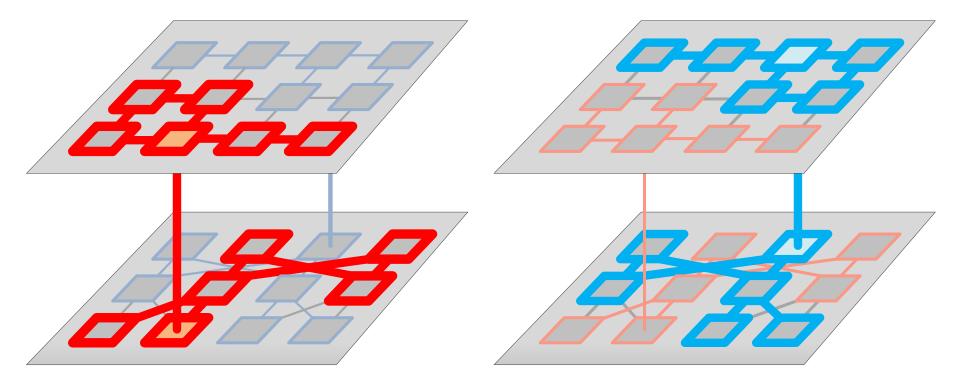


# Network placement on the die



# Vertical regions

Vertical region - subgraph of the entire network, which consists of one node with TSV and nodes attached to it on each die



Red vertical region

Blue vertical region



### Criteria for choosing best solution for full system

The following criteria are applied when we choose best solution for full system:

• **Sum of diameters** [SumD, hops] – the sum of diameters of all **vertical** regions:

SumD=
$$\sum_{i=1}^{P} \max_{v_i,w_i} d(v_i,w_i)$$
  
Where  
d(.) – shortest distance between two nodes  
 $v_i, w_i$  – nodes in i<sup>th</sup> vertical region  
P – the number of TSVs

Different

topologies

 Difference of TSVs load [Δ<sub>VR</sub>, Number nodes] - maximal absolute difference of nodes count among all pairs of vertical regions:

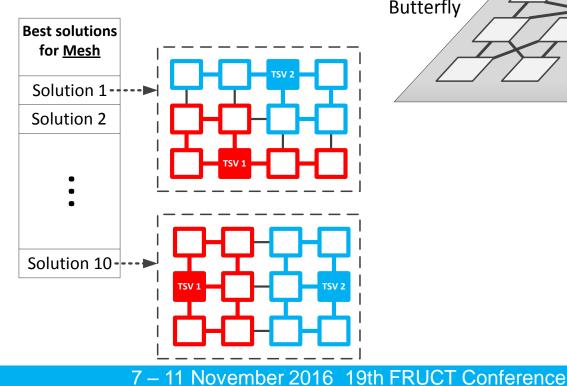
$$\Delta_{VR} = \max_{i \neq j} |n_i - n_j|,$$
Where  
 $n_i = |V_i|, n_j = |V_j|$   
 $V_i, V_j$  - set of nodes in i<sup>th</sup> and j<sup>th</sup> vertical region  
correspondingly

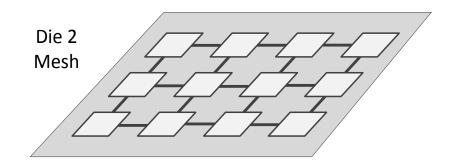


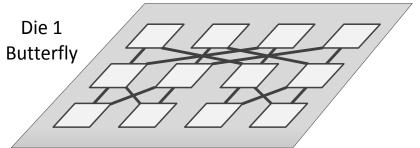
### Placement algorithm (1/4)

It is necessary to place two TSVs (p = 2) in a 3x4 NoC for 2 dies with <u>Mesh</u> and <u>Butterfly</u> topology correspondently, and achieve <u>minimal diameter</u> and <u>minimal</u> <u>load</u> difference of vertical regions.

1. Find set of the best flat solutions for die using the previous algorithm

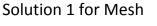






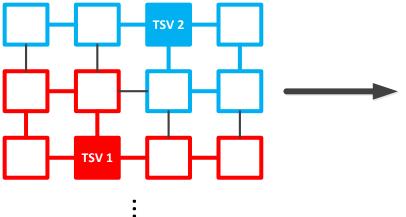


2. Mapping each flat solution from the current die to other dies. Create vertical regions for each solution

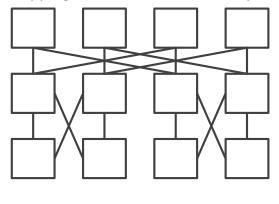


Different

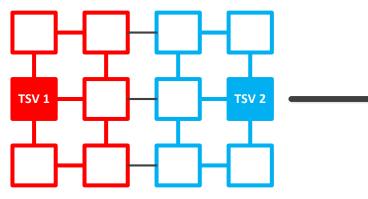
topologies



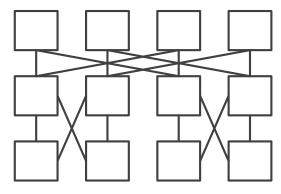
Mapping 1 from Mesh to Butterfly



Solution 10 for Mesh

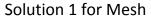


Mapping 10 from Mesh to Butterfly



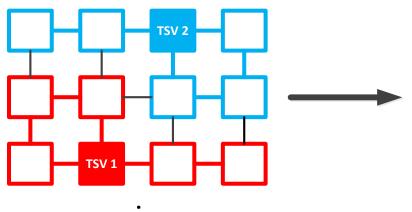


2. Mapping each flat solution from the current die to other dies. Create vertical regions for each solution

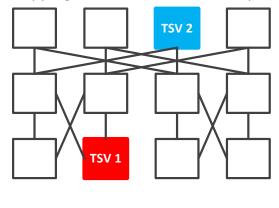


Different

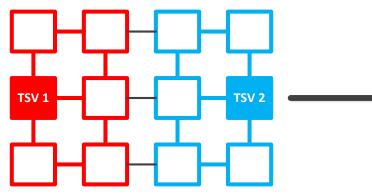
topologies



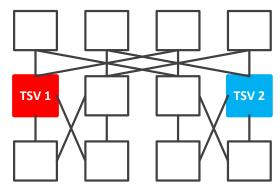
Mapping 1 from Mesh to Butterfly



Solution 10 for Mesh

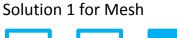


Mapping 10 from Mesh to Butterfly



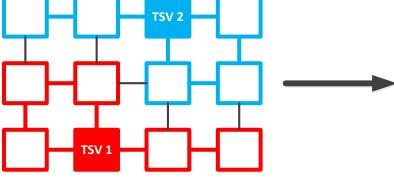


2. Mapping each flat solution from the current die to other dies. Create vertical regions for each solution

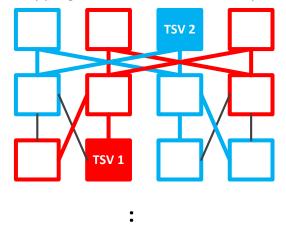


Different

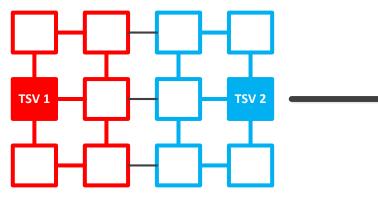
topologies



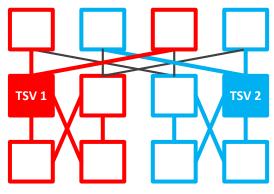
Mapping 1 from Mesh to Butterfly



Solution 10 for Mesh



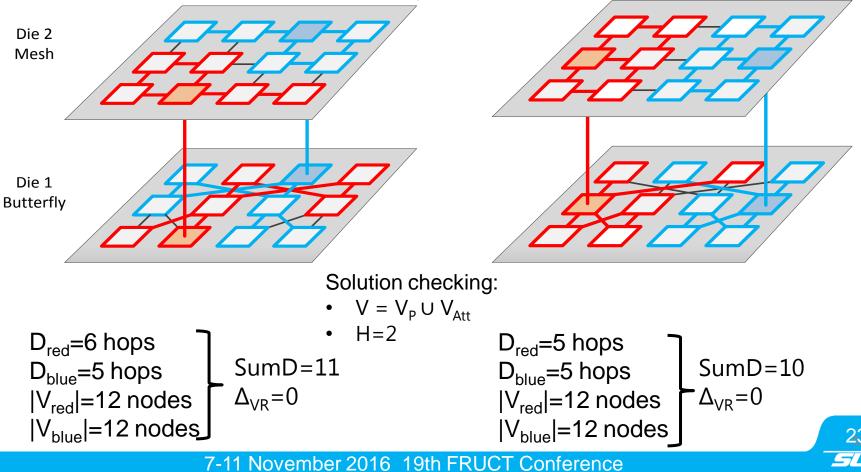
Mapping 10 from Mesh to Butterfly





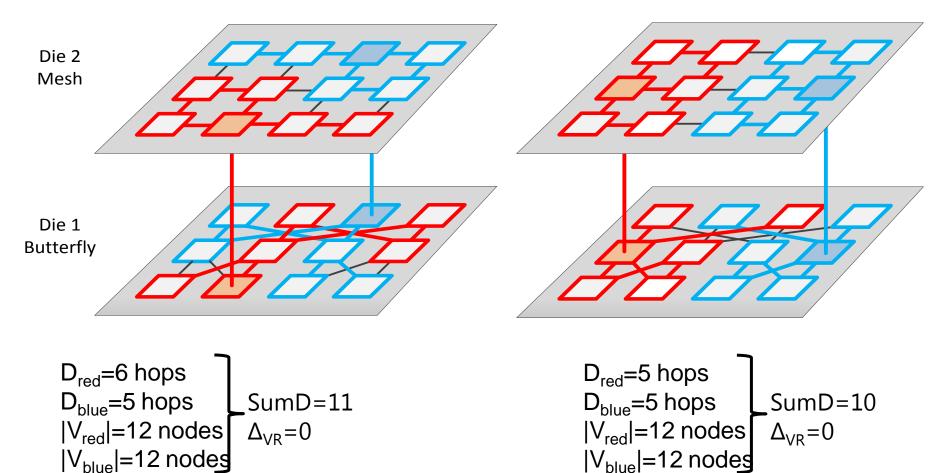
### Placement algorithm (3/4)

- 3. Evaluate each resulting solution by the <u>sum diameters</u> of vertical regions and <u>load difference</u> of TSVs
- 4. Add your resulting solutions to the solutions' set for a full system
- 5. Repeat Steps1-4 for all dies in the system



### Placement algorithm (4/4)

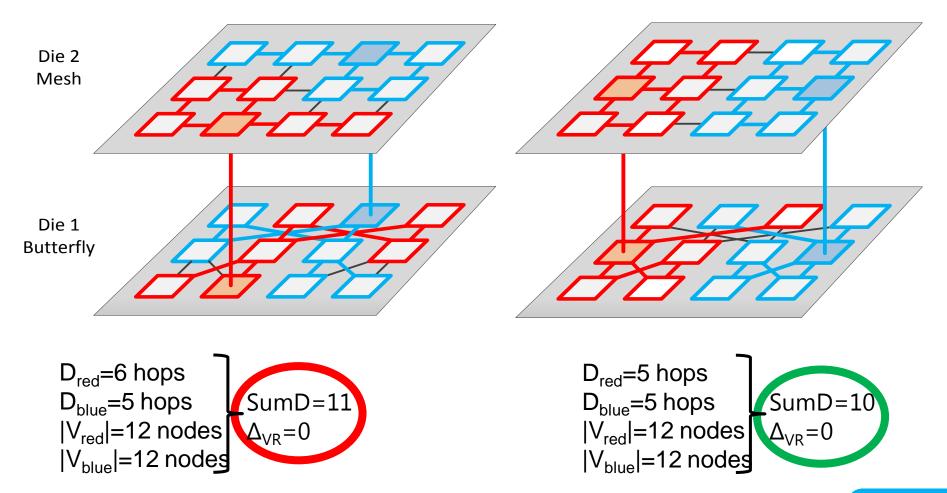
- 6. Filter the solutions' set by minimal sum diameters
- 7. Filter the remaining solutions' set by minimal difference load



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### Placement algorithm (4/4)

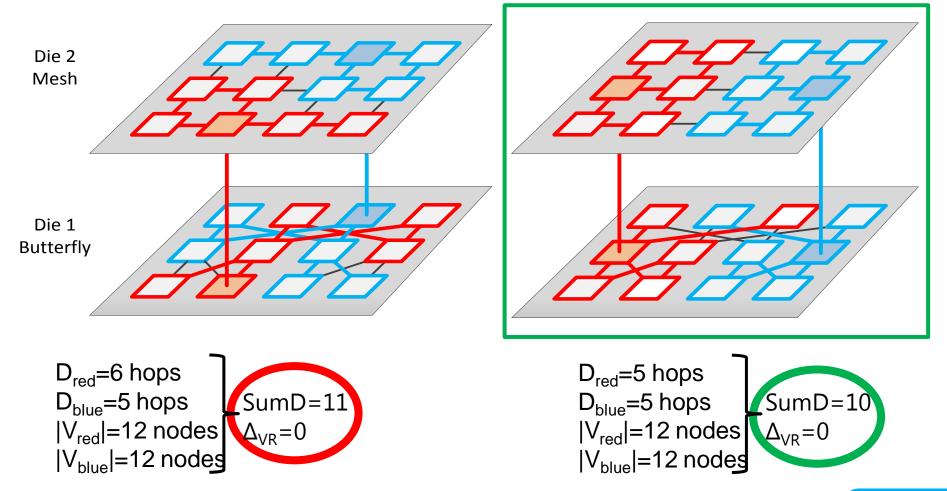
- 6. Filter the solutions' set by minimal sum diameters
- 7. Filter the remaining solutions' set by minimal difference load





### Placement algorithm (4/4)

- 6. Filter the solutions' set by minimal sum diameters
- 7. Filter the remaining solutions' set by minimal difference load





## Conclusion

The aforementioned algorithms solve the following three problems:

- How to place TSV in a 3D NoC?
- How to avoid TSV overheating?
- How to balance the load among TSVs?

	Method for <u>same</u> topologies	Method for <u>different</u> topologies	
Applying	Homogeneous systems-on-chip	Heterogeneous systems-on-chip	
Count of dies	Without limitations	Time consumption depends on a total die count. O(n <sup>2</sup> )	
Count of nodes on the die	≤100		
Count of TSVs	≤5		



## Thank you for your attention!

## Any questions?

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